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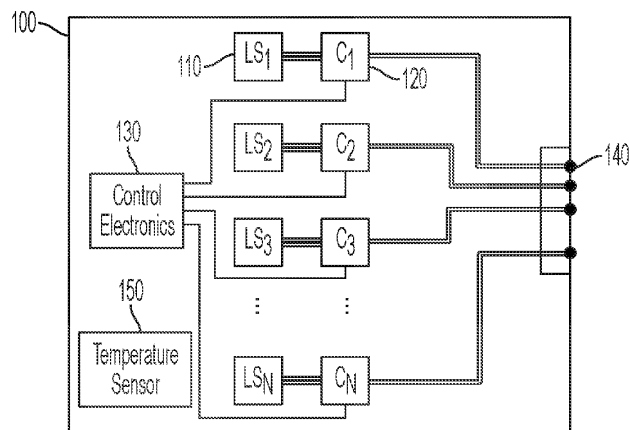


FIG. 1

(57) Abstract: Optical chips and packages are described. The optical chips and packages described herein are configured to output high-power, single mode optical outputs for use by integrated photonics packages. Some embodiments relate to an optical chip or package including a light source array configured to output a plurality of first optical signals and an optical combiner configured to receive the plurality of first optical signals from the light source array and to output a second optical signal that is a combination of the received plurality of first optical signals. The optical combiner may include at least one tunable element configured to increase an optical power of the output second optical signal.

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